

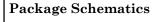


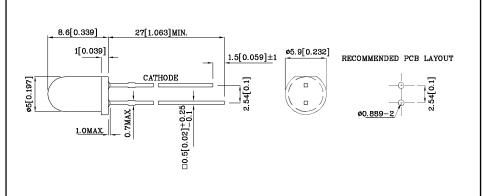
Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant









Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		THI (GaAlAs)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V		
Forward Current	I_{F}	50	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	1200	mA		
Power Dissipation	P_{D}	80	mW		
Operating Temperature	T_{A}	-40 ~ +85	°C		
Storage Temperature	Tstg	-40 ~ +85	1		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

Operating Characteristics (T _A =25°C)	THI (GaAlAs)	Unit		
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.3	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	1.6	V	
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =20mA)	λP	880*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	50	nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	90	pF	

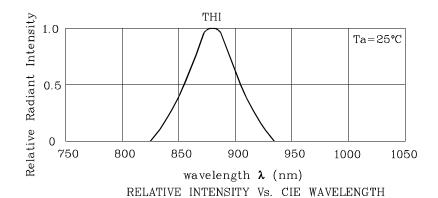
 Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (Po=mW/sr) @20mA		CIE127-2007* CIE127-2007* (Po=mW/sr) (Po=mW/sr)		Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
			min.	typ.	min.	typ.		
XTHI12BF	GaAlAs	Blue Transparent	6*	14*	12*	24*	880*	20°

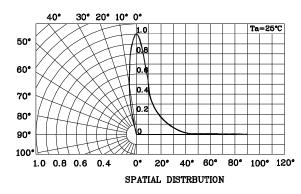
^{*}Radiant intensity value and wavelength are in accordance with CIE127-2007 standards.

Dec 16,2013 XDSA7684 V6-Z Layout: Maggie L.

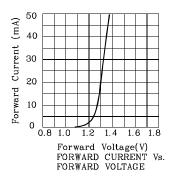


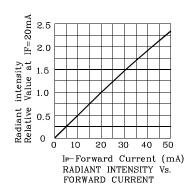


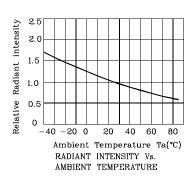




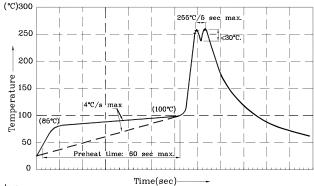
♦ THI







Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes: Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C$ \sim $255^{\circ}C$ for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

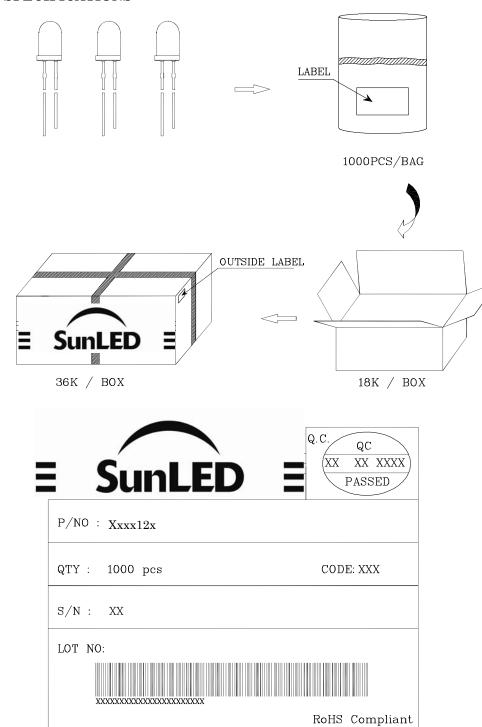
2. Luminous Intensity / Luminous Flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

Dec 16,2013

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

XDSA7684 V6-Z Layout: Maggie L.